Serial No.: 10/565,429

Filing Date: January 18, 2006

Customer No.: 26,289 Attorney's Docket No.: 2003JP317

## Complete set of Claims

[1] (currently amended) A coating composition comprising: a polyalkylsilazane compound; an acetoxysilane compound; and an organic solvent; where said polyalkylsilazane compound contains one or both groups represented by formulae (2) and (3)

$$\frac{R^{8} R^{9}}{\begin{pmatrix} N-Si-R^{10} \end{pmatrix}} \tag{3}$$

wherein R<sup>5</sup> to R<sup>11</sup> each independently represent a hydrogen atom or an alkyl group having 1 to 3 carbon atoms, provided that both R<sup>5</sup> and R<sup>6</sup> do not simultaneously represent hydrogen and all of R9 to R11 do not simultaneously represent hydrogen, and further where the acetoxysilane compound is selected from tetraacetoxysilane, methyltriacetoxysilane, ethyltriacetoxysilane, ethoxytriacetoxysilane, isopropoxytriacetoxysilane, n-butoxytriacetoxysilane, dimethyldiacetoxysilane, diethyldiacetoxysilane, diisopropyldiacetoxysilane, di-nbutyldiacetoxysilane, dimethoxydiacetoxysilane, diethoxyacetoxysilane, diisopropoxydiacetoxysilane, and di-n-butoxydiacetoxysilane, and further where the composition comprises a pore forming agent, and where the pore agent is a siloxy-containing polyethylene oxide compound.

- [2] (canceled)
- [3] (canceled)

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[4] (canceled)

[5] (withdrawn and currently amended) A siliceous material produced by coating a coating composition according to claim 1 onto a substrate or by filling a coating composition according to any one of claims 1 to 4 into a frame or a groove, and firing the coating composition.

- [6] (withdrawn) A semiconductor device comprising a siliceous material according to claim 5 as an intermetal dielectric.
- [7] (withdrawn) A process for producing a siliceous material, comprising heating a coating composition according to claim 1 at a temperature of 350°C or below for 1 to 60 min.
- [8] (cancel).
- [9] (cancel).
- [10] (currently amended) The coating composition according to claim 1 A coating composition comprising: a polyalkylsilazane compound; an acetoxysilane compound; and an organic solvent; where said polyalkylsilazane compound contains one or both groups represented by formulae (2) and (3)

$$\begin{pmatrix}
R^5 \\
S_1 - N - \\
R^6 & R^7
\end{pmatrix}$$
(2)

$$\frac{\mathbb{R}^{8}}{\mathbb{N}^{9}} \mathbb{R}^{9}$$

$$\frac{\mathbb{R}^{1}}{\mathbb{R}^{10}}$$
(3)

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wherein R5 to R11 each independently represent a hydrogen atom or an alkyl group having 1 to 3 carbon atoms, provided that both R5 and R6 do not simultaneously represent hydrogen and all of R9 to R11 do not simultaneously represent hydrogen, and further where the acetoxysilane compound is selected from tetraacetoxysilane, methyltriacetoxysilane. ethyltriacetoxysilane. ethoxytriacetoxysilane, isopropoxytriacetoxysilane, n-butoxytriacetoxysilane, dimethyldiacetoxysilane, diethyldiacetoxysilane, diisopropyldiacetoxysilane, di-nbutyldiacetoxysilane. dimethoxydiacetoxysilane. diethoxyacetoxysilane. diisopropoxydiacetoxysilane, and di-n-butoxydiacetoxysilane, and further where the acetoxysilane compound is in the range 5% to 40% by weight efbased on the weight of the polyalkylsilazane compound.